**HFSS Socket/PCB Model Development Checklist**

COMPANY NAME: Click or tap here to enter text.

1. What is the pitch of the socket?

0.x mm

1. Will the socket be on top (Layer 1) or the bottom of the PCB?

Top (Layer 1) [ ]  Bottom [ ]

1. How many signals are to be simulated ?

1 [ ]  2 [ ]  3 [ ]  4 [ ]  other Click or tap here to enter text.

1. Are the PCB signal(s) single-ended or differential ?

SE [ ]  Differential [ ]

1. Are the PCB signal trace(s) microstrip or stripline?

Microstrip [ ]  Stripline [ ]

1. If the PCB trace design is microstrip, is the transmission line CPWG?

 CPWG [ ]  NON-CPWG [ ]

1. On which PCB layers will signals be launched ?

Click or tap here to enter text.

1. Does the job info contain a PCB stackup (preferably in .XLSX format) ?

YES [ ]  NO [ ]

1. What is the dielectric constant of the PCB material surrounding the signal layers?

Click or tap here to enter text. (or leave blank if info is in stackup file)

1. How many total layers does the PCB have?

Click or tap here to enter text. (or leave blank if info is in stackup file)

1. Please indicate reference/ground layer numbers

Click or tap here to enter text. (or leave blank if info is in stackup file)

1. Please indicate power layer numbers

Click or tap here to enter text. (or leave blank if info is in stackup file)

1. Please indicate signal layer numbers

Click or tap here to enter text. (or leave blank if info is in stackup file)

1. Default signal and via drill diameters are .010” (.25mm)

If different diameters are to be used, please specify:

 Click or tap here to enter text.

1. If vias are not blind vias please specify counterdrill limits (drill to within xx mils/mm):

 Click or tap here to enter text.

1. What is the maximum simulation frequency ?

xx GHz

1. Default target return loss S11 is -20 dB to 20 GHz and -10 dB to 40GHz.

If different targets are desired please specify:

Click or tap here to enter text.

1. Please provide additional comments here:

Click or tap here to enter text.